CLAIMS:

1. A method of manufacturing an electronic device which comprises an electrically insulating body provided with a conductor pattern at a surface, said method comprising the steps of:

- providing a carrier plate with a first side and an opposed second side, with, starting from the first side in that order, a first layer of a first mechanically deformable material and a second layer of a second material different from the first, which second material is patterned substantially in accordance with the conductor pattern and is electrically conducting;

- deforming the carrier plate;

- providing insulating material at the second side of the carrier plate so as to form the electrically insulating body; and

- removing the first layer such that the conductor pattern becomes exposed at the surface of the body.

2. A method as claimed in claim 1, characterized in that the deformation takes place by bending of the carrier plate in at least one direction so as to enclose an angle which is substantially smaller than 180°.

3. A method as claimed in claim 1, characterized in that the deformation of the carrier plate takes place in that the carrier plate is pressed in from the second side of the carrier plate in desired positions by means of a die such that, after the provision of the electrically insulating material, the conductor pattern projects beyond the surface of the body in the desired positions in a direction perpendicular to the surface.

4. A method as claimed in claim 1, characterized in that the second layer is patterned through a local, preferably selective removal of a portion of the second layer from the second side of the carrier plate under formation of a recess, whereupon the formation of the recess is completed by selective etching of a portion of the first layer located in the

recess, during which underetching of the first layer with respect to the remaining portion of the second layer takes place.

5. A method as claimed in claim 4, characterized in that

- the conductor pattern comprises a number of strip-shaped conductors which are each provided with a region of larger dimensions than the width of the strip-shaped conductors, and

- the underetching of the first layer with respect to the remaining portion of the second layer is made so great that the second layer becomes free from the first layer at the areas of the strip-shaped portions of the strip-shaped conductors, whereas the second layer is still connected to the first layer at the areas of the connection regions, whereupon the strip-shaped portions of the strip-shaped conductors are entirely enveloped during the provision of the insulating material.

6. A method as claimed in claim 1 or 2, characterized in that the conductor pattern comprises a number of strip-shaped conductors which are each provided with at least one region having dimensions larger than the width of the strip-shaped conductors.

7. A method as claimed in claim 6, characterized in that the strip-shaped conductors are provided at one end with respective regions serving as connection regions, and said connection regions are placed in a closed arrangement, preferably rectangular, on a first planar surface of the insulating body, a number of said strip-shaped conductors extending further to a second planar surface which encloses an angle with the first planar surface which is substantially smaller than 180°.

8. A method as claimed in claim 1, characterized in that a thickness of between 10 and 300 μm is chosen for the first layer of the carrier plate and a thickness of between 2 and 20 μm for the second layer.

9. A method as claimed in claim 1, characterized in that an electronic element is provided on or above the carrier plate, at the second side thereof, before the insulating material is provided against the carrier plate, which element is electrically connected to the conductor pattern and is surrounded by the insulating material which thus acts as a passivating envelope for the electronic element.

10. A method as claimed in claim 1, characterized in that after the removal of the first layer at least one electrical component is fastened to the electrically insulating body, such that connection regions of the component are connected with electrical conduction to the conductor pattern of the body.

11. An electronic device comprising an electronic element and an electrically insulating body provided with a conductor pattern, characterized in that the insulating body has an enclosed angle which is substantially smaller than 180^0, thus defining a first and a second surface, the conductor pattern (1) extending over said first and second surface.

12. An electronic device as claimed in claim 11, wherein the insulating body (2) provided with a conductor pattern (1) is provided with an opening (20), on the two sides of which a photosensitive semiconductor element (30) and an optical lens (40), respectively, are fastened to the insulating body.

13. An electronic device comprising an electronic element and an electrically insulating body provided with a conductor pattern, characterized in that the conductor pattern projects beyond the surface of the body in desired positions in a direction perpendicular to the surface.